REVISION OF SECTION 702

CHIP SEAL EMULSION

Section 702 of the Standard Specifications is hereby revised for this project as follows:

Subsection 702.02(b) shall include the following:

The Chip Seal emulsion shall be ♠

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INSTRUCTIONS TO DESIGNERS (delete instructions and symbols from final draft):

Use this project special provision to specify the emulsion(s) that will be allowed in the project.

♠ Insert any or all of the following:

 For rapid set emulsions – CRS-2, CRS-2P, CRS-2R

 For medium set emulsions - HFMS-2P

If more than one type of emulsions specified, use either “Chip Seal Emulsion – Rapid Set” or “Chip Seal Emulsion – Medium Set” for pay item, otherwise use the specific pay item for that one particular emulsion specified.